

*A1*  
impedance matching planar circuit between the via hole and the signal transmission line.--

Please replace the paragraph beginning on page 9, line 3, with the following rewritten paragraph:

*A2*  
--A planar impedance matching circuit is constructed of the rectangular stubs 303 and the impedance matching microstrip line 304. A via hole connecting portion is constructed of the via hole 110, the via hole metal pad 102, the via hole metal pad 202, the via hole metal pad 302, the rectangular stubs 303 and the impedance matching microstrip line 304.--

Please replace the paragraph beginning on page 10, line 5, with the following rewritten paragraph:

*A3*  
--Fig. 5 shows the decibel value of reflection loss (S11) and the decibel value of transmission loss (S21) in the case where the length of the impedance matching microstrip line 304 (shown in Fig. 4) is 180  $\mu\text{m}$  and the length of the rectangular stubs 303 (shown in Fig. 4) is 100  $\mu\text{m}$ . For the sake of comparison, Fig. 6 shows a transmission characteristic in the case where no planar impedance matching circuit is provided. In Fig. 5 and Fig. 6, the horizontal axis represents frequency, while the vertical axis represents the reflection loss and the transmission loss.--

Please replace the paragraph beginning on page 12, line 22, with the following rewritten paragraph:

*A4*  
--A planar impedance matching circuit is constructed of the impedance matching microstrip lines 404 and 405. A via hole connecting portion is

*A4*  
constructed of the via hole 410, via hole metal pad 402, via hole metal pad 502, via hole metal pad 602 and impedance matching microstrip lines 404 and 405.--

Please replace the paragraph beginning on page 14, line 16, with the following rewritten paragraph:

*A5*  
--Furthermore, in the aforementioned first and second embodiments, the characteristic impedance of the via hole connecting portion is matched to the characteristic impedance of the microstrip transmission line to which the via hole connecting portion is connected and which is served as the signal transmission line. However, it is acceptable to match the characteristic impedance of the via hole connecting portion with the characteristic impedance of a planar circuit that is connected directly to the via hole connecting portion through no signal transmission line.--

Please replace the paragraph beginning on page 15, line 1, with the following rewritten paragraph:

*A6*  
--As is apparent from the above, according to the high-frequency multilayer circuit substrate of the present invention, the characteristic impedance of the via hole connecting portion, which is constructed of the via hole and the planar circuit, can be matched to the characteristic impedance of the transmission line with a simple structure in terms of design and manufacturing. As a result, low-reflection low-loss inter-circuit-layer transmission in a microwave region, particularly in the millimeter wave region, can be achieved with a simple structure, allowing the manufacturing cost to be reduced. Furthermore, this high-

*Al  
and* frequency multilayer circuit substrate can be effectively utilized for the development of circuits and packages in the microwave region, particularly in the millimeter wave region.--

---